



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE7276-2D			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000669540							
<b>Package</b>	PG-TO252-5-11			<b>Weight*</b>	356.51 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.671	0.47	0.47	4688	4688
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		574	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.29	57.37	572898	573644
wire	non noble metal	aluminium	7429-90-5	0.176	0.05	0.05	493	493
encapsulation	organic material	carbon black	1333-86-4	1.417	0.40		3974	
	plastics	epoxy resin	-	24.793	6.95		69543	
	inorganic material	silicondioxide	60676-86-0	115.463	32.39	39.74	323872	397389
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14228	14228
plating	non noble metal	nickel	7440-02-0	0.076	0.02		214	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	215
solder	noble metal	silver	7440-22-4	0.083	0.02		234	
	non noble metal	tin	7440-31-5	0.067	0.02		187	
	non noble metal	lead	7439-92-1	3.181	0.89	0.93	8922	9343
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com